.050" × .100" Tripolarized, Latch/Ejector Header

Straight, 4 Wall 810 Series



- Tripolarization to mini socket high walls to protect pins
- 50 mil × 100 mil doubles board density
- Nine sizes (20–100 position)
- Latch and eject for rugged high performance applications
- Post mount option facilitates soldering process
- Two row design saves board space

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Physical

Insulation

Material: High Temperature Plastic (LCP)

Flammability: UL 94V-0

Color: Ivory (Natural) - LCP

Marking: 3M Logo, Part Number and Orientation Triangle

Contact

Material: Copper Alloy

Plating

Underplate: 100 μ" [2.54 μm] Nickel — QQ-N-290, Class 2

Wiping Area: 30 μ" [0.76 μm] Gold — MIL-G-45204, Type II, Grade C

Solder Tails: $100 \,\mu'' \, [\, 2.54 \,\mu m \,] \, 90/10 \, Tin \, Lead$

Electrical

Current Rating: 0.5 A

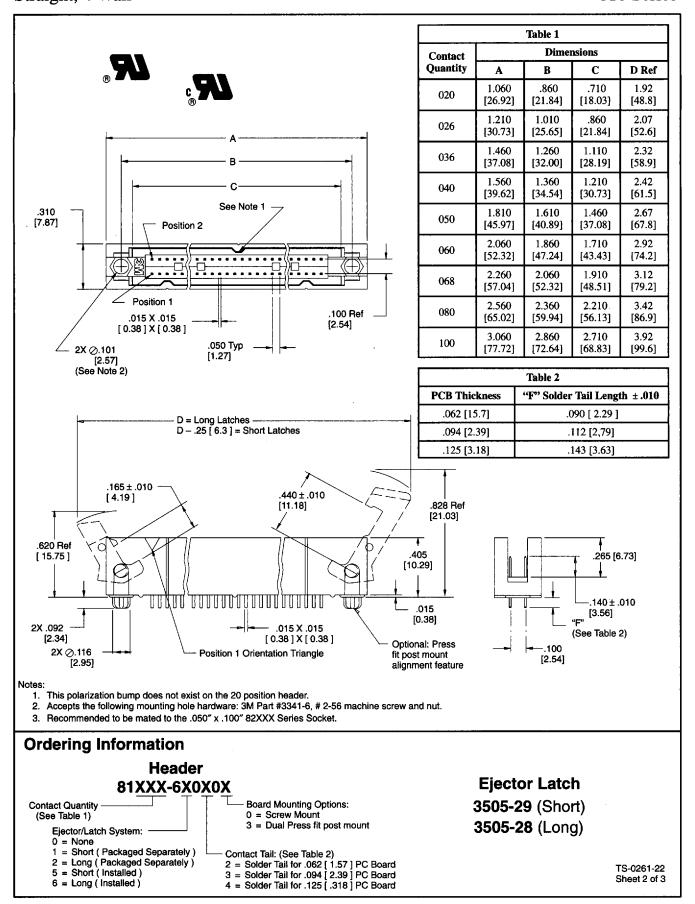
Insulation Resistance: $> 1 \times 10^9 \Omega$ at 500 Vdc **Withstanding Voltage:** 500 Vrms at Sea Level

Environmental

Operating Temperature Rating: -55°C to +105°C

Process Temperature Rating: 250°C @ 90 Seconds Max

UL File No.: E68080



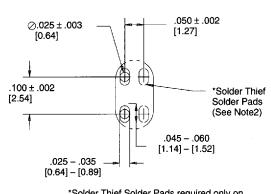
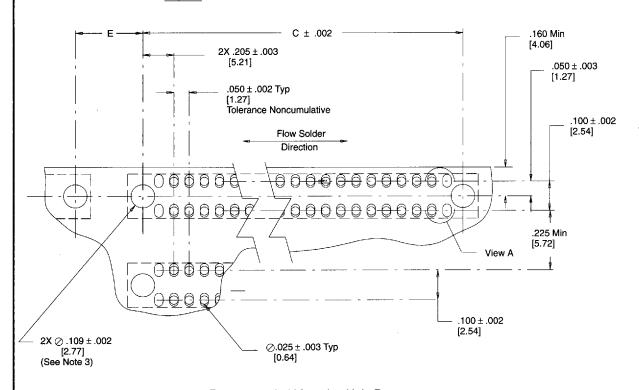


Table 3			
Ejector/Latches Dimension E (Min)			
None	.215 [5.46]		
Long	.650 [16.51]		
Short	.525 [13.34]		

*Solder Thief Solder Pads required only on Solder side of PC Board.

View A



Recommended Mounting Hole Pattern

(Shown for mounting side of PC Board)

Inch [mm]

Tolerance Unless Noted				
	.0	.00	.000	
Inch	± .1	± .01	± .005	
[1 D: : (

[] Dimensions for Reference only

Notes:

- Recommended to process PC Boards through the solder bath such that the connector enters end first (two solder tails at a time).
 This will help prevent solder bridging.
- A Solder Thief Solder Pad (Dummy Pad) at the end of each row is recommended on the bottom or solder side of the PC Board in order to help prevent solder bridging on the end solder tails. The Solder Thiefs are only required on the end of the rows which leave the solder bath last.

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